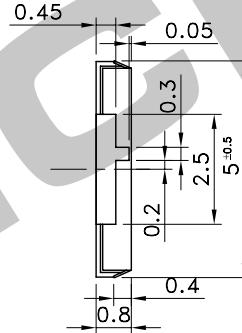
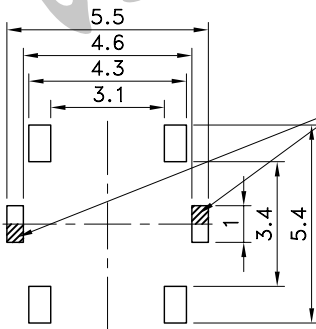


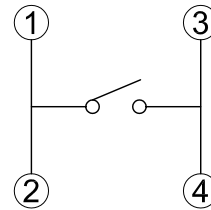
P.C.B TERMINAL POSITION



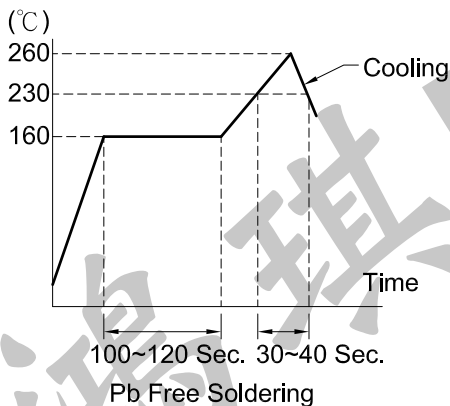
CIRCUIT ARRANGEMENT



GROUND PIN:
 The thickness of cream solder: 150~200 μ
 We recommend to connect the GND land shown in the switch spec. with the GND of your P.C.B for withstanding electric-static discharge.



REFLOW SOLDERING CONDITIONS



SPECIFICATIONS

- | | |
|--------------------------|---|
| 1. Rating | : DC 15V 20mA |
| 2. Contact Resistance | : 50mΩ Max. |
| 3. Insulation Resistance | : 50MΩ Min. at DC 100V |
| 4. Dielectric Strength | : AC 250V for 1 Minute |
| 5. Operating Force | : 260±50gf |
| 6. Circuit | : SPST |
| 7. Stroke | : 0.25 ^{+0.1} _{-0.2} mm |
| 8. Life | : 200,000 Cycles |
| 9. Taping | : 5,000 Pcs/Reel |

REVISION:		DATE:		REVISION:		DATE:	
UNIT:mm		THIRD ANGLE PROJECTION METHOD		TOL. UNLESS OTHERWISE STATED:±0.3		CODE NO.:HCH-140-2	
ISSUED		CONFIRMED		HCH ® HORNG CHIH ISO9001 Certified ISO14001 Certified 鴻琪股份有限公司		PART NO.	
<i>Elvis</i> 2005.07.11		<i>Joey</i> 2005.07.11				STS-06-B	